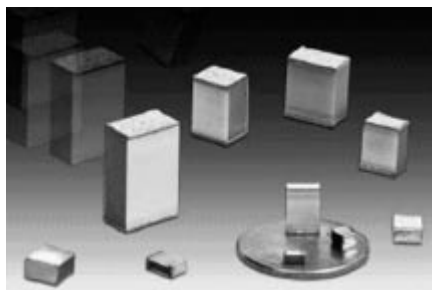


Type FCN Material Content Declaration 1913 thru 6040

Stacked Metallized Film (PEN) Chips for Reflow Soldering

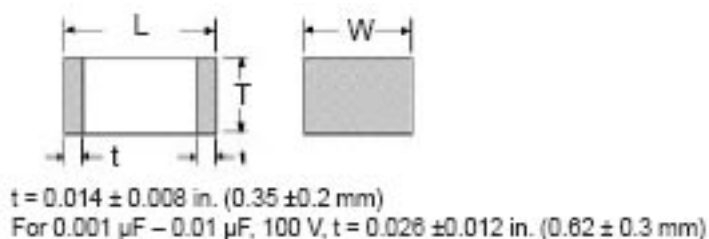


Material Content for RoHS Compliant Parts

Construction Element	Material Group	Materials	CAS if Applicable	Typical Mass (Wt. %)	ppm	Sum (%)
Active Part	Metals	Al (metal spray)	7429-90-5	.6	6000	51
	Polymers	PEN	25853-85-4	50.4	504000	
Termination	Metals	Cu/Zn (metal spray)		19.3	193000	49
	Metals	Cu/Ag/P (metal spray)		19.7	197000	
	Metal	Sn/Ag/Cu (Plating)		10	100000	
					Total	100.0

Case Sizes, Weight and Outline Drawing

Case Size LxW (mm)	Weight (mg)
1913	52.6 - 106.6
2416	94.4 - 170.4
2420	208.1 - 255.4
2820	145.3 - 252.2
2825	318.3 - 453.3
3022	284.6 - 334.4
3925	338.6 - 573.5
3931	632.1 - 760.5
6031	742.4 - 882.2
6040	1053 - 1277



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To the best of our knowledge, the information provided on the enclosed is correct as of the date indicated on the document. Since some of the information is provided by the acceptance of data from sources outside of Cornell Dubilier Electronics, we can not guarantee that all is complete and accurate.